

## S2C-SMT 3.50/08/180G 1.5SN BK RL

Weidmüller Interface GmbH & Co. KG

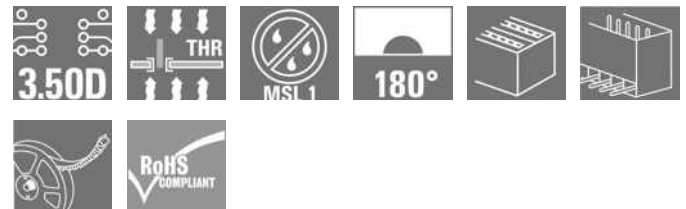
Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

### Product image



### High-temperature-resistant pin header.

- touch-safe
- can be plugged into B2CF 3.50 PUSH IN female plug
- Plug-in direction is perpendicular or parallel to the circuit board (180° / 90°)
- Housing variants: closed (G) and with solder flange (LF)
- Box packaging (BX) or, anti-static, tape-on-reel (RL)
- Suitable for reflow and wave soldering applications
- Pin length of either 1.5 mm or 3.5 mm

### General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, Number of poles: 8, 180°, Solder pin length (l): 1.5 mm, tinned, black, Tape
Order No.	<a href="#">1358880000</a>
Type	S2C-SMT 3.50/08/180G 1.5SN BK RL
GTIN (EAN)	4050118162158
Qty.	175 pc(s).
Product data	IEC: 200 V / 13.4 A UL: 150 V / 10 A
Packaging	Tape

Creation date September 1, 2023 8:27:12 AM CEST

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**Technical data**
**Dimensions and weights**

Depth	10.8 mm	Depth (inches)	0.425 inch
Height	15.7 mm	Height (inches)	0.618 inch
Height of lowest version	14.2 mm	Width	15.4 mm
Width (inches)	0.606 inch	Net weight	2.445 g

**Temperatures**

Operating temperature, min.	-50 °C	Operating temperature, max.	120 °C
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**System specifications**

Product family	OMNIMATE Signal - series B2C/S2C 3.50 - 2-row	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 inch	Outgoing elbow	180°
Number of poles	8	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.0 mm, Octagonal	Solder pin dimensions = d tolerance	+0,01 / -0,03 mm
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (D)	+ 0,1 mm
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	10.5 mm	L1 in inches	0.413 inch
Number of rows	1	Pin series quantity	2
Touch-safe protection acc. to DIN VDE 57 106	finger-safe unplugged/ back-of-hand-safe plugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged
Can be coded	Yes	Plugging force/pole, max.	5 N
Pulling force/pole, max.	5 N		

**Material data**

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIb
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	120 °C	Temperature range, installation, min.	-40 °C
Temperature range, installation, max.	120 °C		

**Rated data acc. to IEC**

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	13.4 A
Rated current, min. number of poles (Tu=40°C)	12 A	Rated voltage for surge voltage class / pollution degree II/2	200 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	80 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 80 A

Creation date September 1, 2023 8:27:13 AM CEST

Catalogue status 18.08.2023 / We reserve the right to make technical changes.

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**Technical data****Rated data acc. to CSA**

Institute (CSA)



Certificate No. (CSA)

200039-1121690

Rated voltage (Use group B / CSA) 150 V

Rated voltage (Use group C / CSA) 50 V

Rated voltage (Use group D / CSA) 150 V

Rated current (Use group B / CSA) 9.5 A

Rated current (Use group C / CSA) 9.5 A

Rated current (Use group D / CSA) 9.5 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

**Rated data acc. to UL 1059**

Institute (cURus)



Certificate No. (cURus)

E60693

Rated voltage (Use group B / UL 1059) 150 V

Rated voltage (Use group C / UL 1059) 50 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group C / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

**Packing**

ESD Level packaging static dissipative

Packaging Tape

VPE length 330 mm

VPE width 330 mm

VPE height 38 mm

Tape depth (T2) 19.8 mm

Tape width (W) 32 mm

Tape pocket depth (K0) 19.3 mm

Tape pocket height (A0) 11.1 mm

Tape pocket width (B0) 19.5 mm

Tape pocket separation (P1) 20 mm

Tape hole separation (E) 1.75 mm

Tape pocket separation (F) 14.2 mm

Tape reel diameter  $\varnothing$  (A) 330 mmSurface resistance  $R_s = 10^9 - 10^{12} \Omega$ Width Pick & Place Pad ( $W_{PPP}$ ) 10 mmLength Pick & Place Pad ( $L_{PPP}$ )

15.6 mm

Diameter of the withdrawal surface ( $\varnothing$ ) $D_{max}$  9 mmProtrusion 1 Pick & Place Pad ( $L_{01(PPP)}$ ) 7.8 mmProtrusion 2 Pick & Place Pad ( $P_{02(PPP)}$ ) 7.8 mm**Classifications**

ETIM 6.0 EC002637

ETIM 7.0 EC002637

ETIM 8.0 EC002637

ECLASS 9.0 27-44-04-02

ECLASS 9.1 27-44-04-02

ECLASS 10.0 27-44-04-02

ECLASS 11.0 27-46-02-01

ECLASS 12.0 27-46-02-01

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## Technical data

### Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	<ul style="list-style-type: none"> <li>• Gold-plated contact surfaces on request</li> <li>• Rated current related to rated cross-section &amp; min. No. of poles.</li> <li>• Spacing between rows: see hole layout</li> <li>• P on drawing = pitch</li> <li>• Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.</li> <li>• Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months</li> </ul>

### Approvals

Approvals



ROHS	Conform
UL File Number Search	UL Website
Certificate No. (cURus)	E60693

### Downloads

Approval/Certificate/Document of Conformity	<a href="#">Declaration of the Manufacturer</a>
Engineering Data	<a href="#">CAD data – STEP</a>
Product Change Notification	<a href="#">Changeover to ESD bags for "Tape on Reel" products</a> <a href="#">Umstellung auf ESD-Beutel bei „Tape on Reel“ Produkten</a>
Catalogues	<a href="#">Catalogues in PDF-format</a>
Brochures	<a href="#">FL DRIVES EN</a> <a href="#">MB SMT EN</a> <a href="#">FL DRIVES DE</a> <a href="#">MB DEVICE MANUF. EN</a> <a href="#">FL BUILDING SAFETY EN</a> <a href="#">FL APPL LED LIGHTING EN</a> <a href="#">FLIndustr.CONTROLS EN</a> <a href="#">FL MACHINE SAFETY EN</a> <a href="#">FL HEATING ELECTR EN</a> <a href="#">FL APPL INVERTER EN</a> <a href="#">FL_BASE_STATION EN</a> <a href="#">FL ELEVATOR EN</a> <a href="#">FL POWER SUPPLY EN</a> <a href="#">FL 72H SAMPLE SER EN</a> <a href="#">PO OMNIMATE EN</a> <a href="#">PO OMNIMATE EN</a>
White paper surface mount technology	<a href="#">Download Whitepaper</a>

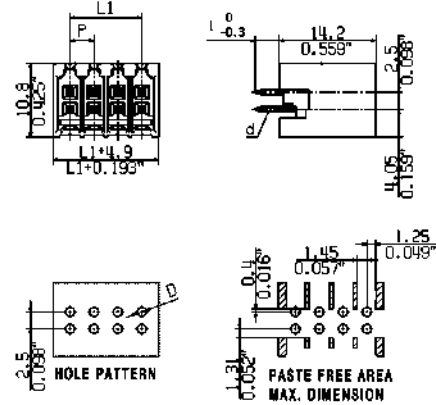
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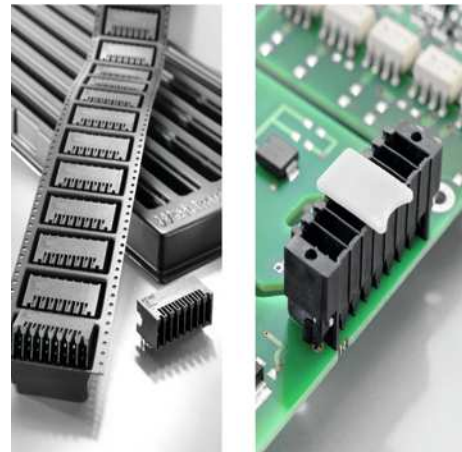
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**Drawings**

**Dimensional drawing**

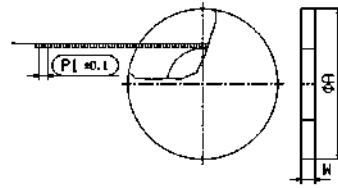


**Product benefits**

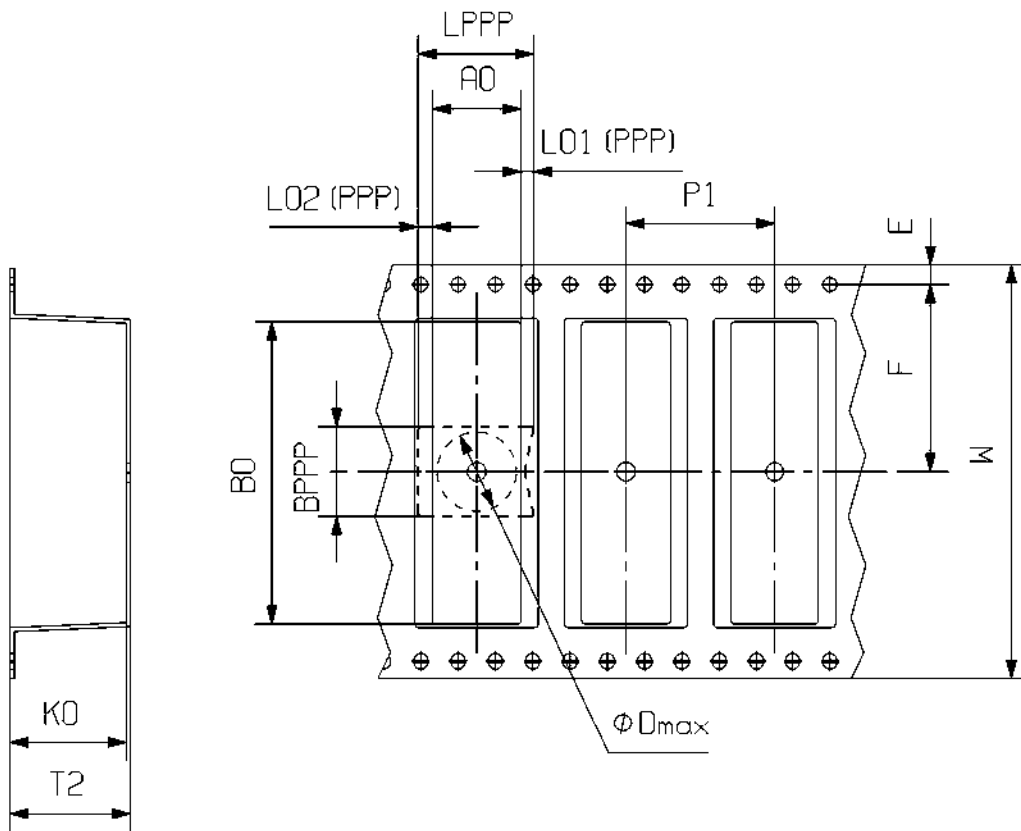


Optimised for the SMT process  
 Safe board-to-board connection

**Dimensional drawing**



**Dimensional drawing**



**DIRECTION OF UNREELING** →

## Recommended wave soldering profiles

**Weidmüller Interface GmbH & Co. KG**  
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 Germany  
 Fon: +49 5231 14-0  
 Fax: +49 5231 14-292083  
 www.weidmueller.com

### Single Wave:



### Double Wave:



### Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

## Recommended reflow soldering profile

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### Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.